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## 2SB1614

## Silicon PNP epitaxial planer type

For low-frequency amplification

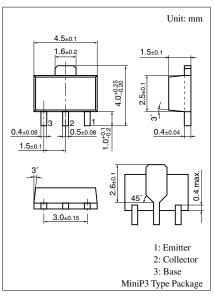
#### ■ Features

- Large collector power dissipation P<sub>C</sub>
- ullet Low collector to emitter saturation voltage  $V_{CE(sat)}$
- Mini power type package, allowing downsizing and thinning of the equipment and automatic insertion through the tape packing

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Collector to base voltage	V <sub>CBO</sub>	-20	V
Collector to emitter voltage	V <sub>CEO</sub>	-20	V
Emitter to base voltage	V <sub>EBO</sub>	-5	V
Peak collector current	$I_{CP}$	-2.4	A
Collector current	$I_{C}$	-2	A
Collector power dissipation *	$P_{\rm C}$	1	W
Junction temperature	T <sub>j</sub>	150	°C
Storage temperature	T <sub>stg</sub>	-55 to +150	°C

Note) \*: Printed circuit board copper foil for collector portion area: 1.0 Cm<sup>2</sup> or more, thickness: 1.7 mm



Marking Symbol: 2K

### ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector cutoff current	I <sub>CBO</sub>	$V_{CB} = -7 \text{ V}, I_E = 0$			- 0.1	μΑ
Collector to base voltage	V <sub>CBO</sub>	$I_C = -10 \mu\text{A},  I_E = 0$	-20			V
Collector to emitter voltage	V <sub>CEO</sub>	$I_{\rm C} = -1  \text{mA},  I_{\rm B} = 0$	-20			V
Emitter to base voltage	V <sub>EBO</sub>	$I_E = -10 \ \mu A, I_C = 0$	-5			V
Forward current transfer ratio	h <sub>FE</sub>	$V_{CE} = -2 \text{ V}, I_C = 200 \text{ mA}$	200		800	
Collector to emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = -1 \text{ A}, I_B = -20 \text{ mA}$		- 0.15	- 0.25	V
Collector output capacitance	C <sub>ob</sub>	$V_{CB} = -6 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		68		pF
Transition frequency	$f_T$	$V_{CB} = -6 \text{ V}, I_E = 50 \text{ mA}, f = 200 \text{ MHz}$		60		MHz

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